

04-23-2003



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11002 U.S. PTO  
10/413562



To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

<p>1. Name of Conveying Party(ies): <b>4-15-03</b>  <b>(1) Yasuhiko KOUNO, (2) Hideo MIURA,</b>  <b>(3) Nobuyoshi MATSUURA and</b>  <b>(4) Masaharu KUBO</b>          Additional names of conveying parties attached: <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and Address of Receiving Party(ies):          Name: <b>Hitachi, Ltd.</b>          Address: <b>6, Kanda Surugadai 4-chome</b>  <b>Chiyoda-ku, Tokyo, Japan</b></p>
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3. Nature of Conveyance:

Assignment       Merger  
 Security Agreement     Change of Name  
 Other:

Execution Date: **(1) March 5, 2003 (2) March 17, 2003; (3) March 1, 2003 and (4) March 10, 2003**

4. (a) Patent Application Number(s):  
**10413562**  
 If this document is being filed together with a new application, the execution dates of the application are:  
 Additional Numbers Attached.

4. (b) Patent Numbers:

5. Name and Address of Party to whom Correspondence Concerning this Document Should be Mailed:

Name: **Stanley P. Fisher**

Address: **Reed Smith LLP**  
**3110 Fairview Park Dr.**  
**Suite 1400**  
**Falls Church, Va. 22042**

6. Total Number of Applications and Patents Involved: **1**

7. Total Fee: **\$40.00**  
 (37 C.F.R. § 3.41)

Enclosed.  
 Authorized to be charged to deposit account.

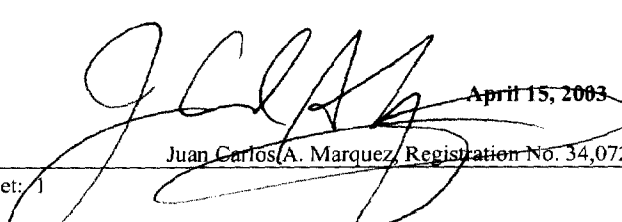
8. Deposit Account Number: **08-1480**

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9. Statement and Signature:

*To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true copy of the original document.*

 **April 15, 2003**

Stanley P. Fisher, Registration No. 24, 344      **Juan Carlos(A. Marquez, Registration No. 34,072**

Total number of pages comprising cover sheet: **1**

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ASSIGNMENT  
( 譲渡証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR WAFER AND MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

- |   |                      |
|---|----------------------|
| 1) <u>Yasuhiko Kouno</u> Yasuhiko KOUNO         | <u>5/March/2003</u>  |
| 2) <u>Hideo Miura</u> Hideo MIURA               | <u>17/March/2003</u> |
| 3) <u>Nobuyoshi Matsuura</u> Nobuyoshi MATSUURA | <u>1/March/2003</u>  |
| 4) <u>Masaharu Kubo</u> Masaharu KUBO           | <u>10/March/2003</u> |
| 5) _____  | _____                |
| 6) _____  | _____                |
| 7) _____  | _____                |
| 8) _____  | _____                |
| 9) _____  | _____                |
| 10) _____                                       | _____                |